

Amendments to the Specification:

Please insert the following paragraph on page 1 prior to the paragraph entitled “Technical Field”:

RELATED APPLICATIONS

This is a Divisional application of co-pending prior U.S. Application No. 10/035,704 (Atty. Dkt. No. 01-471/LSI1P172), entitled “MULTI-STEP PROCESS FOR FORMING A BARRIER FILM FOR USE IN COPPER LAYER FORMATION”, filed on October 18, 2001, which is incorporated herein by reference and from which priority under 35 U.S.C. § 120 is claimed.

Please replace paragraph [0037] with the following amended paragraph:

[0037] Another embodiment can deposit the bulk copper layer 203 using electroless copper deposition. One method of accomplishing such electroless deposition of copper is disclosed in U.S. Patent Application No. 10/035,705, (Attorney Docket No. 01-473/LSI1P173), entitled “Electroless Deposition of Copper to Form Copper Interconnect Structures”, filed ~~concurrently herewith~~ on October 18, 2001 and hereby incorporated by reference. The inventors contemplate that other techniques known to those having ordinary skill in the art can be used to form the bulk copper layer 203.